



<b>Title of Change:</b>	Final PCN for wire change from gold to copper and part number change.									
<b>Proposed first ship date:</b>	10 July 2015									
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or < Yasuhiro Igarashi @onsemi.com >									
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office									
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or < Kazutoshi.Kitazume@onsemi.com >.									
<b>Type of notification:</b>	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <PCN.Support@onsemi.com>.									
<b>Change Part Identification:</b>	Affected products will be identified with new part number (changing suffix to "-W").									
	<table border="1"> <thead> <tr> <th>PART_ID</th> <th>New Part_ID</th> </tr> </thead> <tbody> <tr> <td>ECH8315-TL-H</td> <td>ECH8315-TL-W</td> </tr> <tr> <td>ECH8659-TL-H</td> <td rowspan="2">ECH8659-TL-W</td> </tr> <tr> <td>ECH8659-M-TL-H</td> </tr> </tbody> </table>			PART_ID	New Part_ID	ECH8315-TL-H	ECH8315-TL-W	ECH8659-TL-H	ECH8659-TL-W	ECH8659-M-TL-H
PART_ID	New Part_ID									
ECH8315-TL-H	ECH8315-TL-W									
ECH8659-TL-H	ECH8659-TL-W									
ECH8659-M-TL-H										
<b>Change category(s):</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____									
<b>Sites Affected:</b>	<b>Site 1</b>	<b>Site 2</b>								
<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input checked="" type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s):	ON Shenzhen, China									
<b>Description and Purpose:</b>										
This is a Final Process Change Notification to announce for below contents. 1) Changing wire material from gold to copper 2) Changing part number from XXXXXX-TL-H to XXXXXX-TL-W.										
<b>Reliability Data Summary:</b>										
Test	Conditions	Results								
Steady State Operating Life	Tj=150degC	1000 hrs	Pass							
High Temperature Reverse Bias	Ta=150degC,VR=max	1000 hrs	Pass							
Temp Humidity Storage	Ta=85degC, RH=85%	1000 hrs	Pass							
Temperature Cycle	Ta=-55degC to 150degC 30min each	100 cycles	Pass							
Pressure Cooker	Ta=121degC,2.03x10 <sup>5</sup> Pa,100%	50 hrs	Pass							
High Temperature Storage	Ta=150degC	1000 hrs	Pass							
Resistance to Soldering heat(Reflow)	Solder Temp.:260degC±5degC	10s	Pass							
Solderability	Solder Temp.: 245degC±5degC	5 s	Pass							
<b>Electrical Characteristic Summary:</b>										
Electrical characteristics are not impacted.										
<b>List of Affected Standard Parts:</b>										
ECH8315-TL-H										
ECH8659-TL-H										
ECH8659-M-TL-H										